

SOLDER WIRE HF32-SMD

Very low, pale and dry residues after soldering

DESCRIPTION

The solder wire HF32-SMD meets the highest requirements for safe residues. The low flux content results in virtually residue-free soldering. "In-Circuit" Tests will not be influenced by any residues of Stannol Solder Wire HF32-SMD.

CHARACTERISTICS

- **Flux Residues** (maximum 1% flux content still provides good solder flow. If residue removal is really considered necessary, Stannol Flux-Ex 200B (CFC free) or most conventional organic solvents can be applied.)
- **Halide-free** (corrosion resistance and excellent insulation properties assure lasting reliability of the soldered parts.)
- **Non-poluting** (No cleaning operation necessary)

PHYISCAL PROPERTIES AND DATA

GENERAL PROPERTIES	SOLDER WIRE HF32-SMD	
Flux type:	ROL0 / J-STD-004	
Flux content:	Standard 1.0 % ± 0.3 %	
Halide content:	None / J-STD-004	
Corrosion effect:	None / J-STD-004	
Surface Insulation Resistance:	85°/85° r.H. 7 d	10 ¹⁰ Ω
Standard alloys acc to. ISO 9453:2014	S-Sn60Pb40	
	S-Sn62Pb36Ag2	
Available diameters:	from 0.23 mm	
Available reel size	250 g, 500 g	

Other alloys, diameters flux contents or reel sizes are available on request.

HEALTH AND SAFETY

Before using please read the material safety data sheet carefully and observe the safety precautions described.

NOTICE

The above values are typical and represent no form of specification. The Data Sheet serves for information purposes. Any verbal or written advise is not binding for the company, whether such information originates from the company offices or from a sales representative. This is also in respect of any protection rights of third parties, and does not release the customer from the responsibility of verifying the products of the company for suitability of use for the intended process or purpose. Should any liability on the part of the company arise, the company will only indemnify for loss or damage to the same extent as for defects in quality.